

Product Specifications

Part Number ⁶	OCL ¹ (nH) ±10%	FLL ² (nH) minimum	I _{rms} ³ (amps)	I _{sat} ^{1,4} (amps)	I _{sat} ^{2,5} (amps)	DCR (mΩ) @20°C
CTX01-18738-R	210	151	50	55	45	0.29 ± 5%

1. Open Circuit Inductance (OCL) Test Parameters: 300kHz, 0.10V_{rms}, 0.0Adc @ 25°C.

2. Full Load Inductance (FLL) Test Parameters: 300kHz, 0.10V_{rms}, I_{sat} 1 @ 25°C.

3. I_{sat}: DC current for an approximate temperature rise of 20°C without core loss. Derating is necessary for AC currents.

PCB layout, trace thickness and width, air-flow and proximity of other heat generating components will affect the temperature rise. It is recommended that the temperature of the part not exceed 125°C under worst case operating conditions verified in the end application.

4. I_{sat}1: Peak current for approximately 20% rolloff at +25°C.

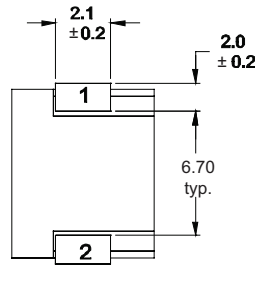
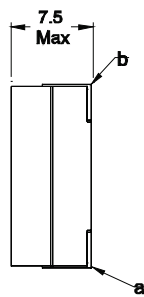
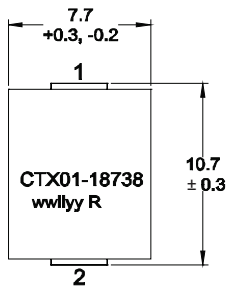
5. I_{sat}2: Peak current for approximately 20% rolloff at +125°C.

6. Part Number Definition: CTX01-18738-R

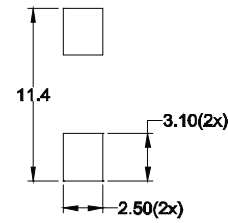
- CTX01-18738 = Product code and size

- "R" suffix = RoHS compliant

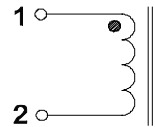
Dimensions (mm)



Recommended Pad Layout

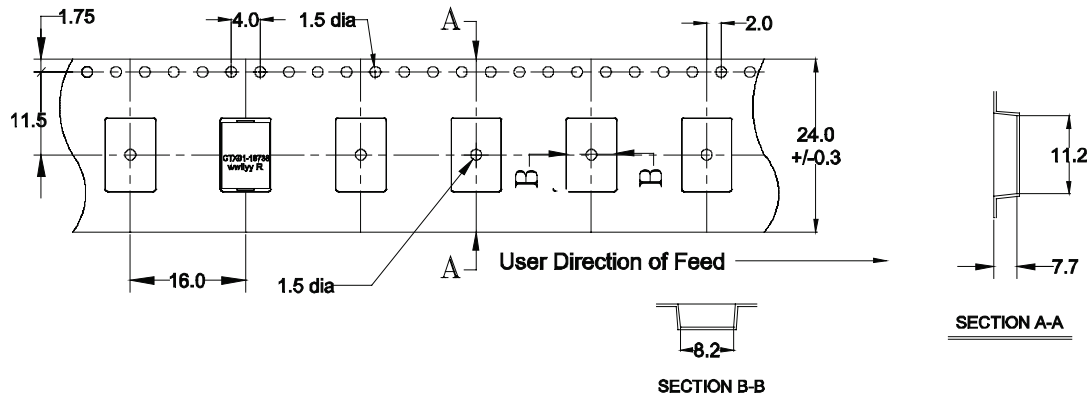


Schematic

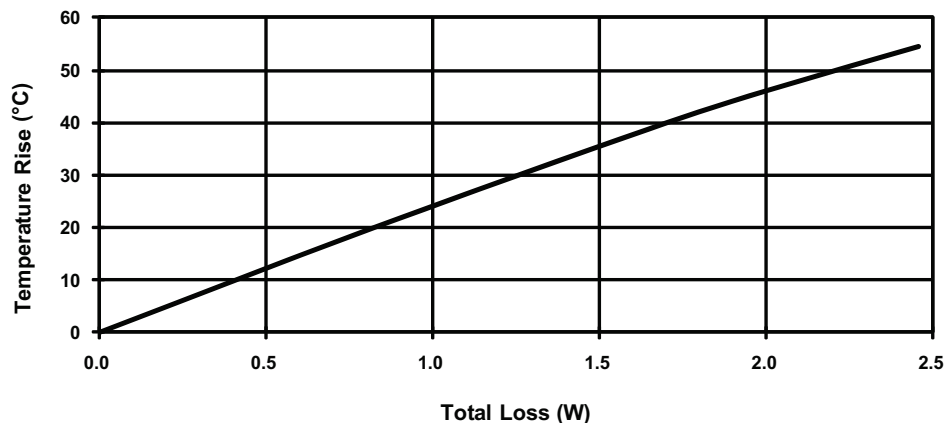


Part marking: CTX01-18738, wwlyy = Date Code, R = Revision Level
All soldering surfaces must be coplanar within 0.102 millimeters.
Tolerances are ±0.1 millimeters unless stated otherwise.
The DCR is measured from point "a" to point "b"

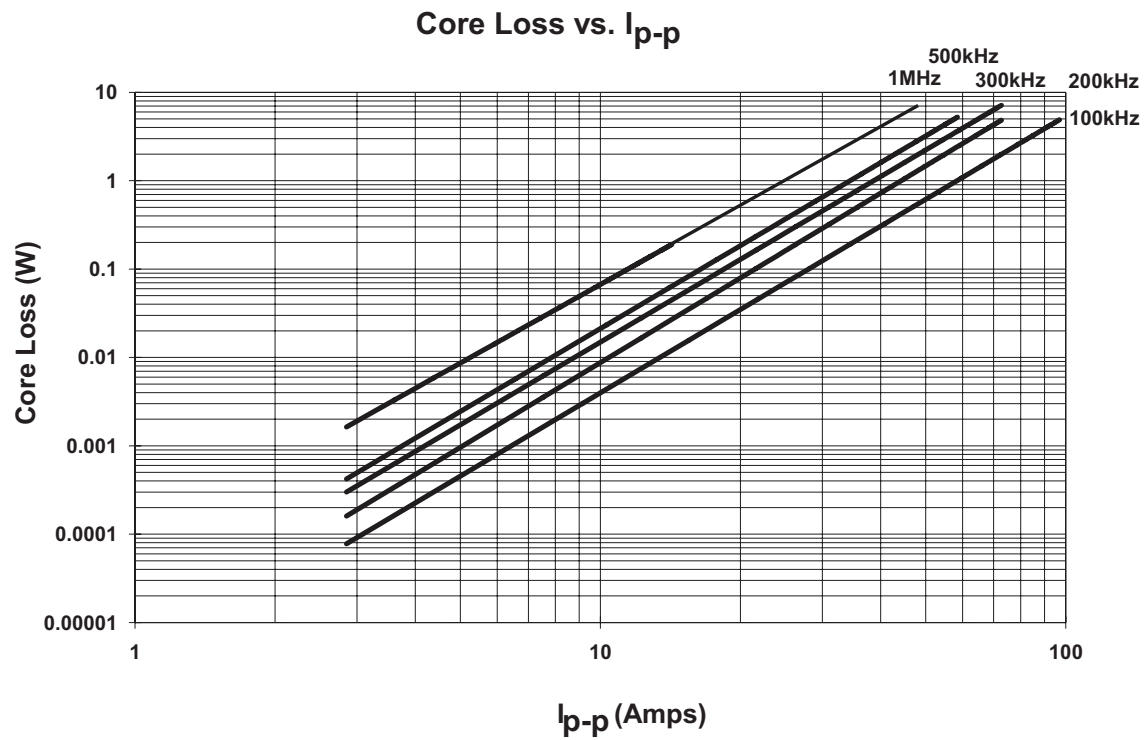
Packaging information (mm)



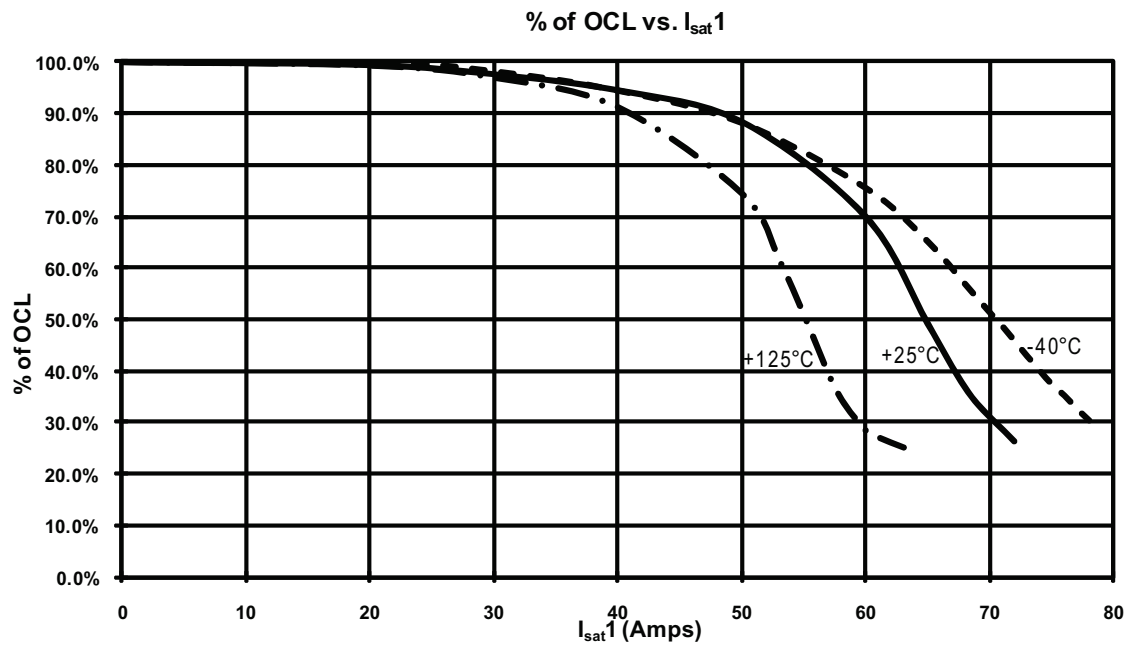
Temperature rise vs. total loss



Core loss



Inductance characteristics



Solder reflow profile

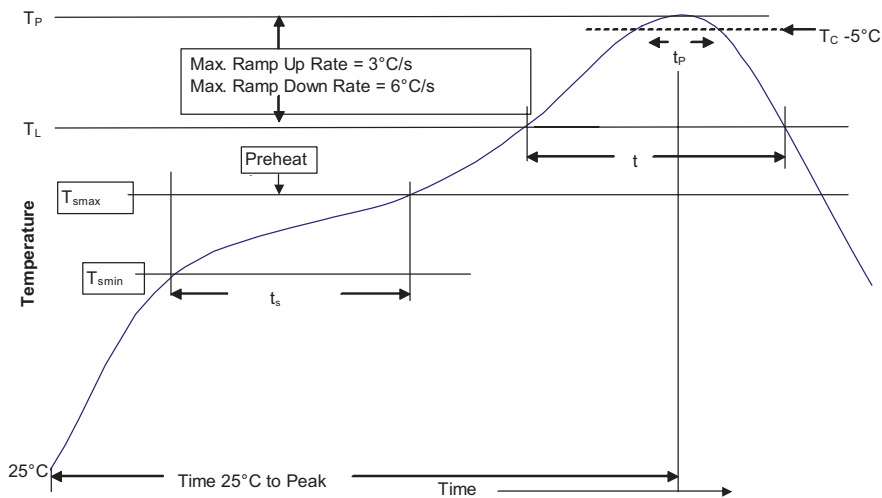


Table 1 - Standard SnPb Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ ≥350
<2.5mm)	235°C	220°C
≥2.5mm	220°C	220°C

Table 2 - Lead (Pb) Free Solder (T_C)

Package Thickness	Volume mm ³ <350	Volume mm ³ 350 - 2000	Volume mm ³ >2000
<1.6mm	260°C	260°C	260°C
1.6 – 2.5mm	260°C	250°C	245°C
>2.5mm	250°C	245°C	245°C

Reference JEDEC J-STD-020D

Profile Feature	Standard SnPb Solder	Lead (Pb) Free Solder
Preheat and Soak		
• Temperature min. (T_{smin})	100°C	150°C
• Temperature max. (T_{smax})	150°C	200°C
• Time (T_{smin} to T_{smax}) (t_s)	60-120 Seconds	60-120 Seconds
Average ramp up rate T_{smax} to T_p	3°C/ Second Max.	3°C/ Second Max.
Liquidous temperature (T_L)	183°C	217°C
Time at liquidous (t_L)	60-150 Seconds	60-150 Seconds
Peak package body temperature (T_p)*	Table 1	Table 2
Time (t_p)** within 5 °C of the specified classification temperature (T_C)	20 Seconds**	30 Seconds**
Average ramp-down rate (T_p to T_{smax})	6°C/ Second Max.	6°C/ Second Max.
Time 25°C to Peak Temperature	6 Minutes Max.	8 Minutes Max.

* Tolerance for peak profile temperature (T_p) is defined as a supplier minimum and a user maximum.

** Tolerance for time at peak profile temperature (t_p) is defined as a supplier minimum and a user maximum.

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